



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-01-29
Contact Name *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Authorized Representative *	Rossana Bonaccorso
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SMP100LC-270	8HZG* CWB270R	A	64BA	2018-01-29
	Amount	UoM	Unit type	ST ECOPACK Grade
	98	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.2-3.7-2.37	2	J bend	
Comment	SMB CLIP (SOD 6)			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.08	Die / Leadframe	837
Lead	2.24	Soft solder	22857

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	8HZG*CW8270R					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	2.266	mg	supplier	die	Silicon (Si)	7440-21-3		2.214	mg	977052	22592
				supplier	metallization	Aluminium (Al)	7429-90-5		0.008	mg	3530	82
				supplier	Passivation	Silicon Oxide	7631-86-9		0.011	mg	4854	112
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.011	mg	4854	112
				supplier	back side metallization	Gold (Au)	7440-57-5		0.004	mg	1766	41
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.018	mg	7944	184
Leadframe	M-004 Copper and its alloys	40.745	mg	supplier	alloy	Copper (Cu)	7440-50-8		40.623	mg	997006	414520
				supplier	alloy	Iron (Fe)	7439-89-6		0.041	mg	1006	418
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.012	mg	294	122
				supplier	metallization	Nickel (Ni)	7440-02-0		0.064	mg	1571	653
				supplier	metallization	Phosphorus (P)	7723-14-0		0.005	mg	123	53
				supplier	alloy	Lead (Pb)	7439-92-1	7a-Lead in high me	2.240	mg	920296	22857
Soft solder	Solder	2.434	mg	JIG - R	solder	Silver (Ag)	7440-22-4		0.061	mg	25062	622
				supplier	solder	Tin (Sn)	7440-31-5		0.121	mg	49712	1235
				supplier	solder	flux residue	Proprietary		0.012	mg	4930	122
				supplier	mold compound	Amorphous Silica	7631-86-9		24.426	mg	731011	249245
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		6.349	mg	190010	64786
				supplier	mold compound	Phenol resin	9003-35-4		1.002	mg	29987	10224
Encapsulation	M-011 Other inorganic materials	33.414	mg	supplier	mold compound	Bisphenol A-bisphenol A diglycidyle ether poly	25036-25-3		1.002	mg	29987	10224
				supplier	mold compound	Carbon black	1333-86-4		0.301	mg	9008	3071
				supplier	mold compound	Triphenylphosphine	603-35-0		0.234	mg	7003	2388
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		0.100	mg	2994	1020
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.811	mg	1000000	8276
				supplier	alloy	Copper (Cu)	7440-50-8		18.330	mg	1000000	187041